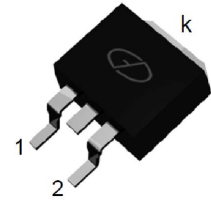


## Features

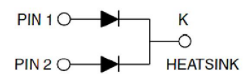
- Plastic package has underwriters Laboratory Flammability Classification 94V-0
- Dual rectifier construction, positive center tap
- Low forward voltage, high efficiency
- Guarding for over voltage protection



Package: TO-263

## Mechanical Data

- Case: epoxy, molded
- Weight: 1.4grams (approximately)
- Lead temperature for soldering purpose: 260°C max. for 10 sec
- 50 units per plastic tube or 800 pcs per reel



Schematic Diagram

## Maximum Ratings & Electrical Characteristics

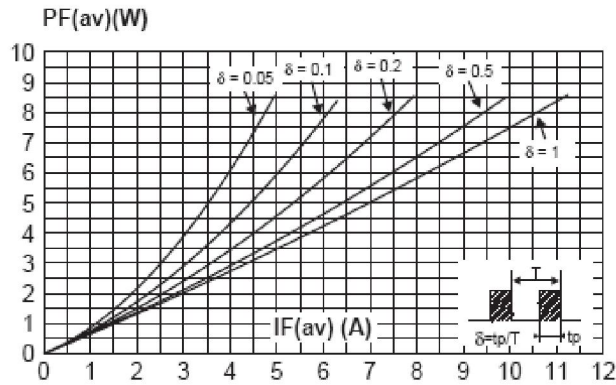
(T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Test Conditions		Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage			V <sub>RRM</sub>	150	V
Working Peak Reverse Voltage			V <sub>RWM</sub>	150	V
Maximum DC Blocking Voltage			V <sub>DC</sub>	150	V
Maximum Average Forward Rectified Current @ T <sub>c</sub> =105°C	Total Device		I <sub>F(AV)</sub>	20	A
	Per Diode			10	
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load per Diode			I <sub>FSM</sub>	150	A
Peak repetitive Reverse Current Per Leg at tp=2.0μs ,1KHz			I <sub>RRM</sub>	1.0	A
Voltage Rate of Change (rated V <sub>R</sub> )			DV/dt	10000	V/μs
Operating Junction Temperature Range			T <sub>J</sub>	- 55 to+150	°C
Storage Temperature Range			T <sub>STG</sub>	- 55 to+150	°C
Maximum Instantaneous Forward Voltage per Leg	I <sub>F</sub> =10A	T <sub>C</sub> =25°C	V <sub>F</sub>	0.92	V
		T <sub>C</sub> =125°C		0.82	
Maximum Reverse Current per Leg at Working Peak Reverse Voltage			I <sub>R</sub>	200	μA
				T <sub>J</sub> =100°C	15
<b>Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)</b>					
<b>Symbol</b>	<b>Parameter</b>	<b>Typ.(TO-263)</b>			<b>Unit</b>
R <sub>θJC</sub>	Thermal Resistance, Junction to Case per Leg	2.0			°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient per Leg	62.5			°C/W

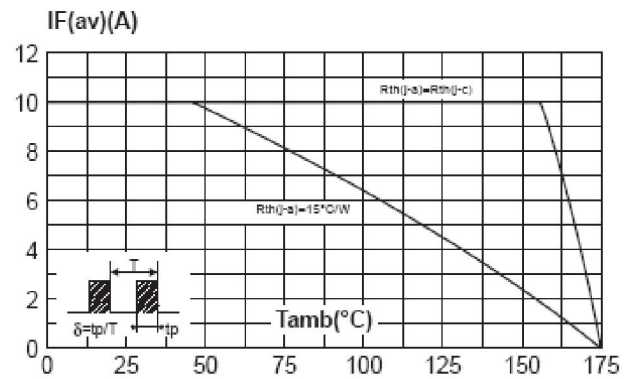
**Note:** Pulse test:300us pulse width, duty cycle=2%

## Ratings and Characteristics Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

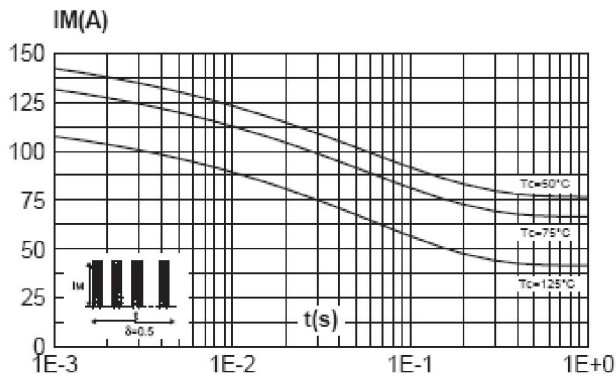
**Fig. 1:** Average forward power dissipation versus average forward current (per diode).



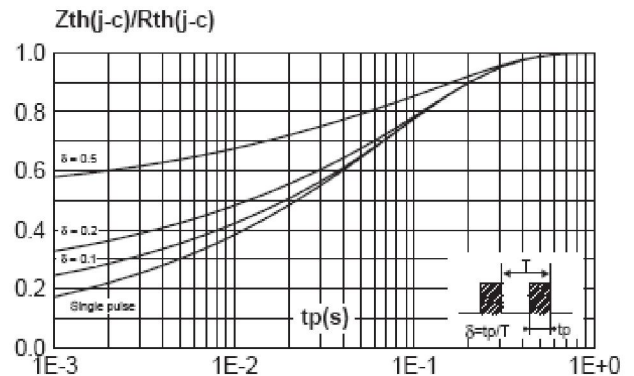
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode).



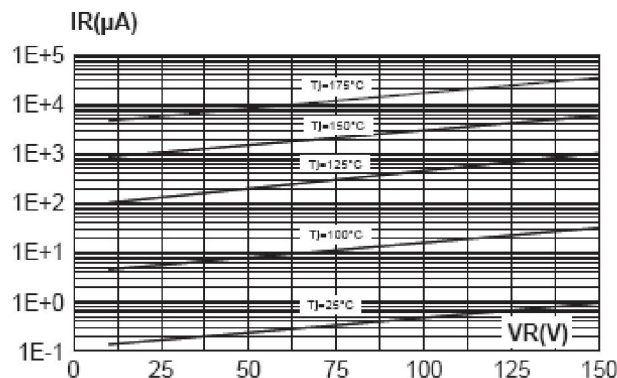
**Fig. 3:** Non repetitive surge peak forward current versus overload duration (maximum values, per diode).



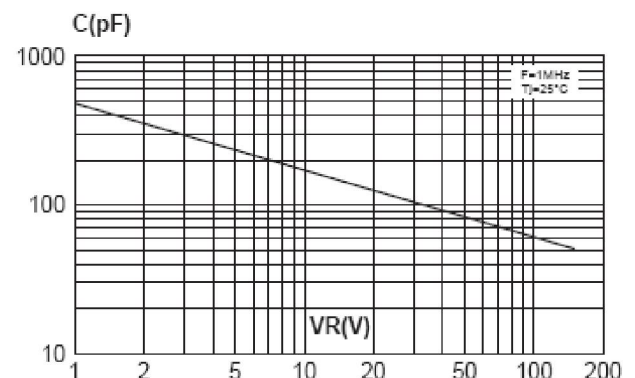
**Fig. 4:** Relative variation of thermal impedance junction to case versus pulse duration (per diode).



**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values, per diode).



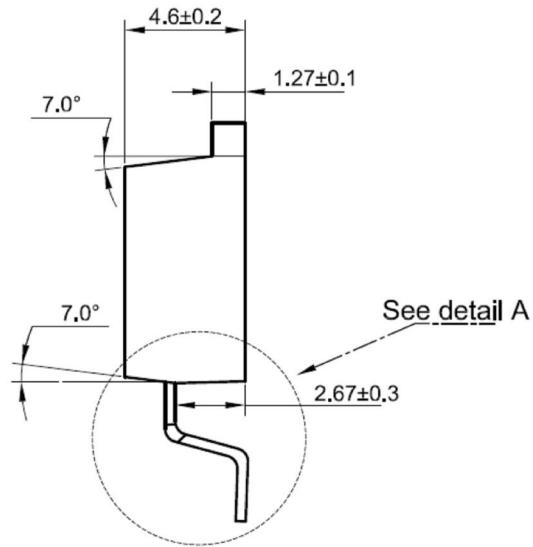
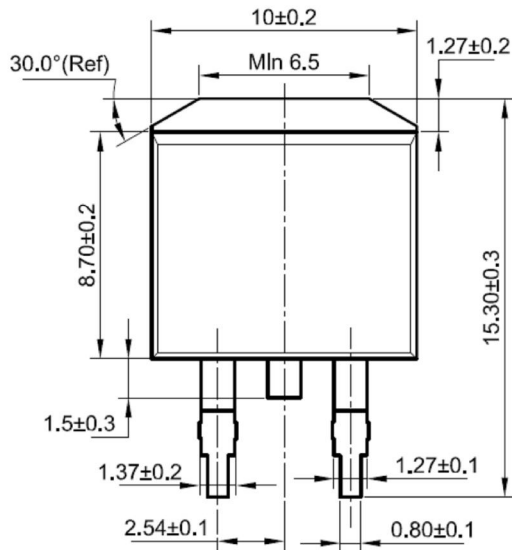
**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values, per diode).



## Package Outline Dimensions

in millimeters

TO-263



### Detail A

